



SIMPLIFY YOUR DUAL INTERFACE CHIP BONDING PROCESS

tesa® HAF 8414

Heat-activated Anisotropic Conductive Film

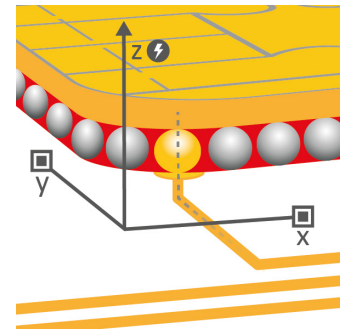
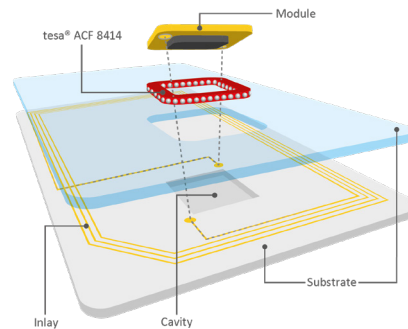
tesa[®] HAF 8414

Chip Bonding And Contacting In One Step

Dual Interface cards require a connection between the antenna and the chip module. For more than 10 years, we have been offering tesa[®] HAF 8414, an Anisotropic Conductive Hotmelt Film, designed for Dual Interface module-embedding processes and adapted to your common implanting lines without investment requirements. Mechanically bonding the module and electrically contacting the antenna are now performed in one single step as easy as the assembly of contact cards.

Applications

- Payment Cards
- Government & Health Cards
- Transportation Cards
- Access Cards



Product Features

- Proven performance in CQM certified cards
- Good workability on all common implanting lines
- Applicable for Dual Interface PVC, ABS, and PC cards
- Suitable for solid and wire contact pads
- Mean particle size of 40um
- Electrically conductive in Z axis only



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